

N-channel SiC power MOSFET

V_{DSS}	1200V
R _{DS(on)} (Typ.)	36mΩ
I _D *1	43A
P_{D}	176W

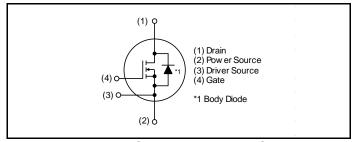
●Outline



Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating; RoHS compliant

•Inner circuit



Please note Driver Source and Power Source are not exchangeable. Their exchange might lead to malfunction.

Application

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating
- Motor drives

Packaging specifications

	Packing	Tube
	Reel size (mm)	-
Typo	Tape width (mm)	-
Type	Basic ordering unit (pcs)	30
	Taping code	C15
	Marking	SCT4036KR

• Absolute maximum ratings $(T_c = 25^{\circ}C)$

	,			
Parameter		Symbol	Value	Unit
Drain - source voltage		V_{DSS}	1200	V
Continuous drain and source current	\ \ _\\	, , *1	43	Α
$T_c = 100$ °C	$V_{GS} = V_{GS_on}$	I _D , I _S *1	30	Α
Pulsed drain current	$V_{GS} = V_{GS_on}$	I _{D,pulse} *2	84	Α
Body diode pulsed forward current	$V_{GS} = 0 V$	I _{S,pulse} *3	43	Α
Body diode surge forward current	$V_{GS} = 0 V$	I _{S,pulse} *4	84	Α
Gate - source voltage (DC)		V_{GSS}	-4 to +21	V
Gate - source surge voltage (t _{surge} < 300ns)		$V_{\rm GSS_surge}^{*5}$	-4 to +23	V
Recommended turn-on gate - source drive voltage		$V_{\rm GS_on}^{*6}$	+15 to +18	V
Recommended turn-off gate - source drive voltage		V_{GS_off}	0	V
Virtual junction temperature		T_{vj}	175	°C
Range of storage temperature		T _{stg}	-40 to +175	°C

ullet Electrical characteristics (T_{vj} = 25°C unless otherwise specified)

Parameter	Symbol	Conditions		Values	Unit	
raiailletei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Drain - Source breakdown voltage	V	$V_{GS} = 0 \text{ V}, I_D = 9.2 \text{mA}$				V
	$V_{(BR)DSS}$	T _{vj} = 25°C	1200	-	-	V
		$V_{GS} = 0 \text{ V}, V_{DS} = 1200 \text{V}$				
Zero Gate voltage Drain current	I _{DSS}	T _{vj} = 25°C	-	1	80	μΑ
Diam carrent		T _{vj} = 150°C	-	10	-	
Gate - Source leakage current	I _{GSS+}	$V_{GS} = +21V , V_{DS} = 0V$	-	-	100	nA
Gate - Source leakage current		$V_{GS} = -4V$, $V_{DS} = 0V$	-	-	-100	nA
Gate threshold voltage	V _{GS (th)} *7	$V_{DS} = 10V, I_D = 11.1mA$	2.8	1	4.8	V
		$V_{GS} = 18V, I_{D} = 21A$				_
Static Drain - Source on - state resistance	R _{DS(on)} *8	T _{vj} = 25°C	-	36	47	mΩ
on oldio recicianes		T _{vj} = 150°C	-	72	-	
Gate input resistance	R_{G}	f = 1MHz, open drain	-	1	-	Ω

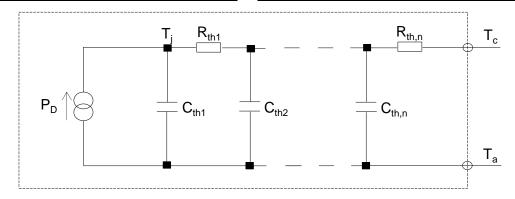
●Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R _{thJC} *9	-	0.65	0.85	K/W

Typical Transient Thermal Characteristics

Symbol	Value	Unit
R _{th1}	1.1 ×10 ⁻¹	
R _{th2}	2.5 ×10 ⁻¹	K/W
R _{th3}	2.9 ×10 ⁻¹	

Symbol	Value	Unit
C _{th1}	5.8 ×10 ⁻⁴	
C _{th2}	2.3 ×10 ⁻³	Ws/K
C _{th3}	1.1 ×10 ⁻²	



Electrical characteristics ($T_{vj} = 25$ °C unless otherwise specified)

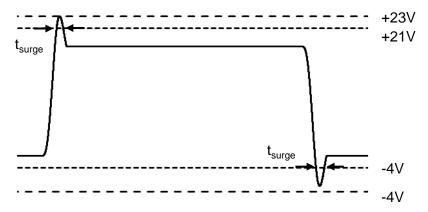
Parameter	Symbol Condition	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Transconductance	g fs *8	$V_{DS} = 10V, I_{D} = 21A$	-	14	-	S
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	2335	-	
Output capacitance	C _{oss}	V _{DS} = 800V	-	70	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	5	-	
Effective output capacitance, energy related	C _{o(er)}	$V_{GS} = 0V$ $V_{DS} = 0V$ to 800V	-	84	-	pF
Total Gate charge	Q _g *8	$V_{DS} = 800V$ $I_{D} = 21A$	ı	91	ı	
Gate - Source charge	Q _{gs} *8	$V_{GS} = 18V$	-	20	-	nC
Gate - Drain charge	Q _{gd} *8	See Fig. 1-1, 1-2.	-	24	-	
Turn - on delay time	t _{d(on)} *8	$V_{DS} = 800V$	ı	8.1	1	
Rise time	t _r *8	$I_D = 21A$ $V_{GS} = +18V / 0V$	ı	15	1	20
Turn - off delay time	t _{d(off)} *8	$R_G = 3.3\Omega$, L = 250µH E_{on} includes diode	ı	29	ı	ns
Fall time	t _f *8	reverse recovery $L_{\sigma} = 50 \text{nH}, C_{\sigma} = 10 \text{pF}$	-	9.6	-	
Turn - on switching loss	E _{on} *8	See Fig. 2-1, 2-2, 2-3.	-	239	-	1
Turn - off switching loss	E _{off} *8		-	26	-	μJ

●Body diode electrical characteristics (Source-Drain) (T_{vj} = 25°C unless otherwise specified)

Parameter	Symbol	Conditions		Values		Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Forward voltage	V _{SD} *8	$V_{GS} = 0V, I_D = 21A$	ı	3.3	-	V
Reverse recovery time	t _{rr} *8	$I_F = 21A$ $V_R = 800V$	1	9.2	ı	ns
Reverse recovery charge	Q _{rr} *8	di/dt = 3700A/µs	-	140	-	nC
Peak reverse recovery current	I _{rrm} *8	$L_{\sigma} = 50$ nH, $C_{\sigma} = 10$ pF See Fig. 3-1, 3-2.	-	31	-	А

^{*1} Limited by maximum T_{vi} and for Max. R_{thJC} .

^{*5} Example of acceptable V_{GS} waveform



Please note especially when using driver source that V_{GSS_surge} must be in the range of absolute maximum rating.

- *6 Please be advised not to use SiC-MOSFETs with V_{GS} below 10V as doing so may cause thermal runaway.
- *7 Tested after applying $V_{GS} = 21V$ for 100ms.
- *8 Pulsed
- *9 Measured conformable to JESD51-14.

See the application note "rthjc_measurement_and_usage_an-e.pdf". Link

 $URL: https://fscdn.rohm.com/en/products/databook/applinote/discrete/common/rthjc_measurement_and_usage_an-e.pdf$

^{*2} $P_W \le 10\mu s$, Duty cycle $\le 1\%$

^{*3} Only for body-diode, Repititive pulse, PW ≤ 500ns, Duty cycle ≤ 5%

^{*4} When used as a protective function, PW \leq 10 μ s

Fig.1 Power Dissipation Derating Curve

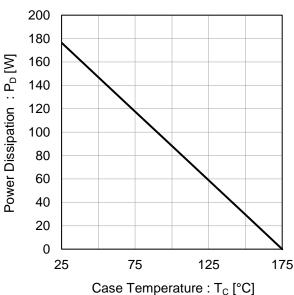


Fig.2 Maximum Safe Operating Area

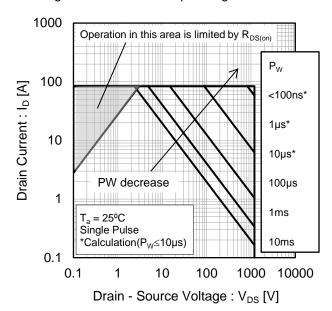
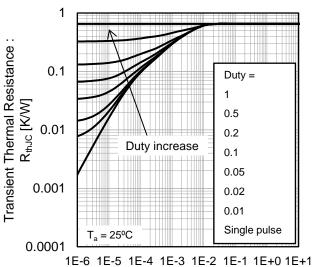
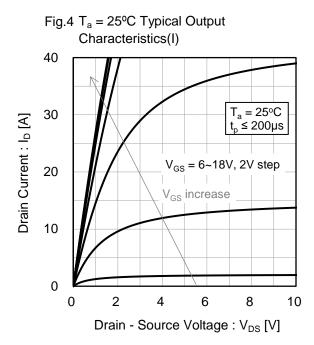


Fig.3 Typical Transient Thermal Resistance vs. Pulse Width



1E-4 1E-3 1E-2 1E-1 1E+0 1E+1

Pulse Width: Pw [s]



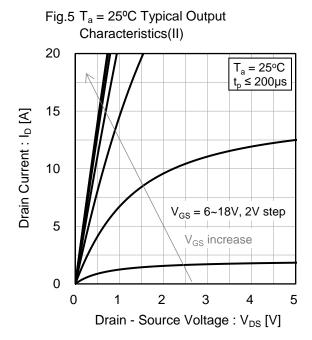
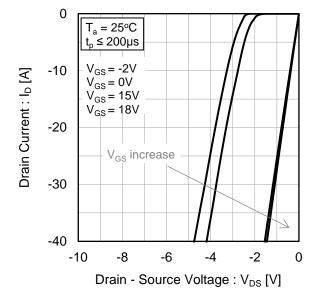
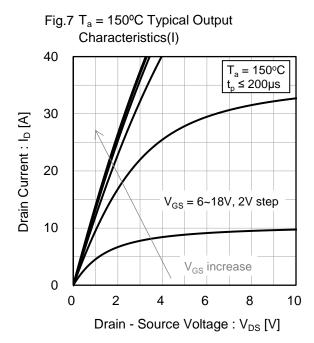
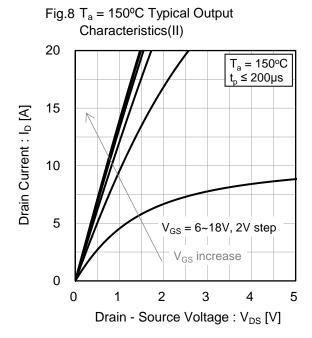
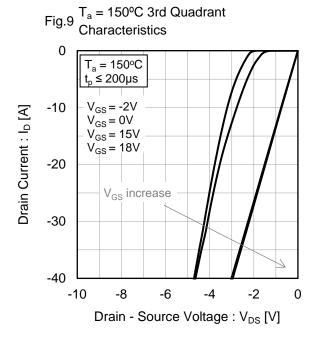


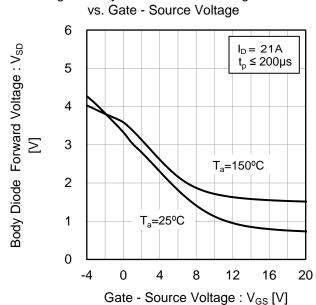
Fig.6 T_a = 25°C 3rd Quadrant Characteristics











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Fig.10 Body Diode Forward Voltage

Fig.11 Typical Transfer Characteristics (I)

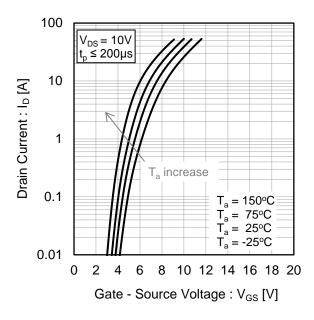


Fig.12 Typical Transfer Characteristics (II)

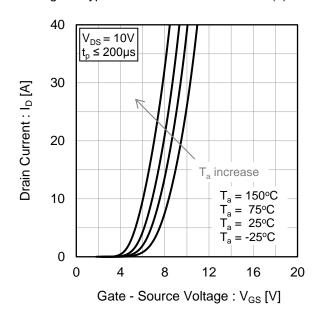


Fig.13 Gate Threshold Voltage vs. Junction Temperature

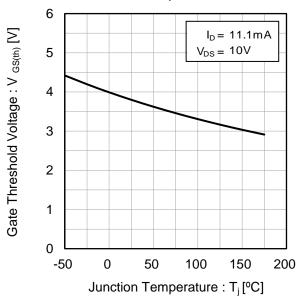


Fig.14 Transconductance vs. Drain Current

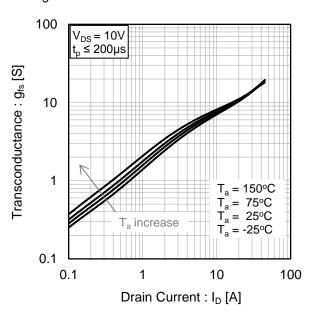


Fig.15 Static Drain - Source On - State Resistance vs. Gate - Source Voltage

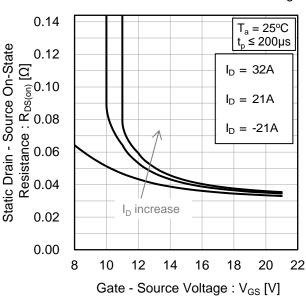


Fig.16 Static Drain - Source On - State Resistance vs. Junction Temperature

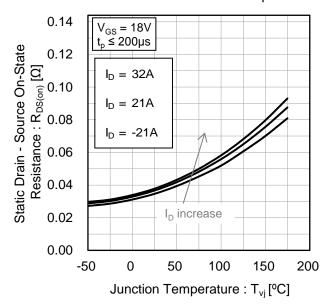


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current

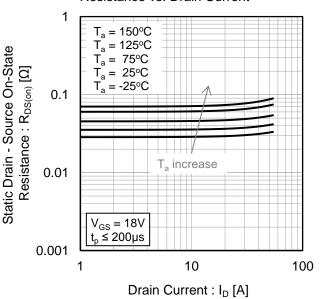
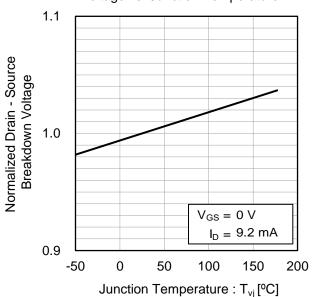
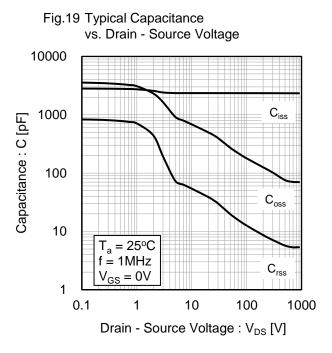


Fig.18 Normalized Drain - Source Breakdown Voltage vs. Junction Temperature





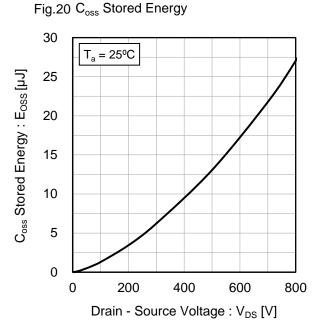


Fig.21 Dynamic Input Characteristics

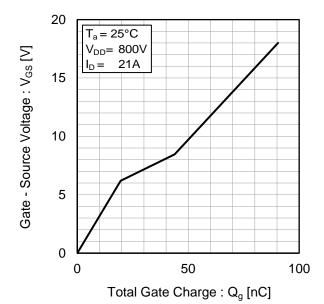


Fig.22 Typical Switching Time vs. External Gate Resistance

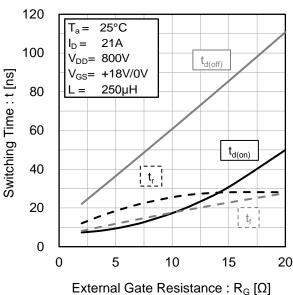
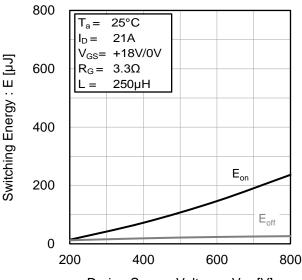


Fig.23 Typical Switching Loss vs. Drain - Source Voltage



Drain - Source Voltage : V_{DS} [V]

Fig.24 Typical Switching Loss vs. Drain Current

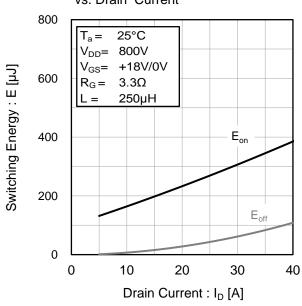
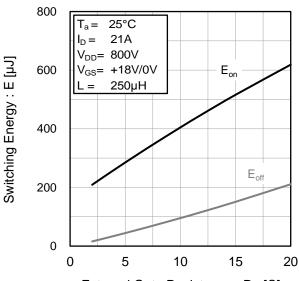


Fig.25 Typical Switching Loss vs. External Gate Resistance



External Gate Resistance : R_G [Ω]

•Measurement circuits and waveforms

Fig.1-1 Gate Charge Measurement Circuit

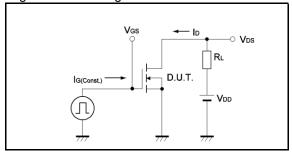


Fig.2-1 Switching Characteristics Measurement Circuit

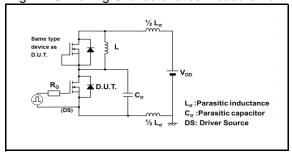


Fig.2-3 Waveforms for Switching Energy Loss

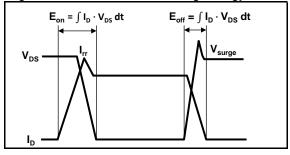


Fig.3-1 Reverse Recovery Time Measurement Circuit

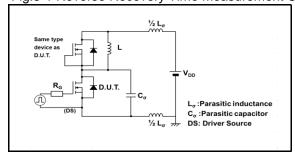


Fig.1-2 Gate Charge Waveform

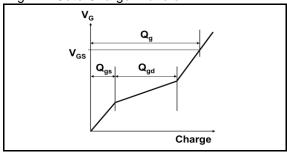


Fig.2-2 Waveforms for Switching Time

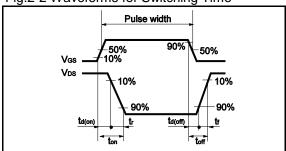
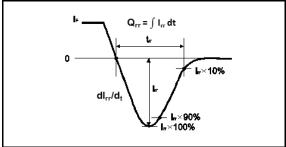
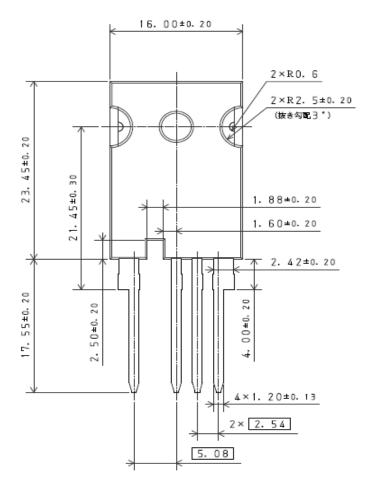
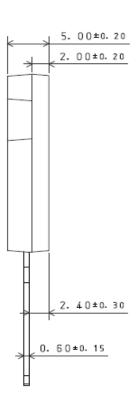


Fig.3-2 Reverse Recovery Waveform

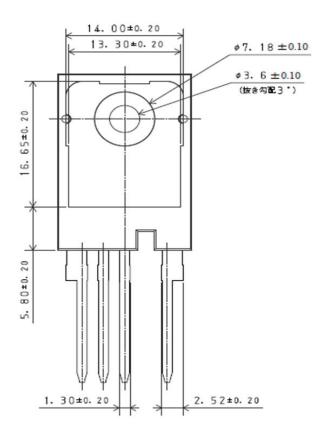


Package Dimensions



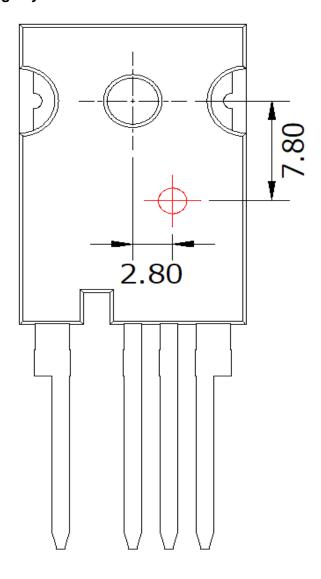


Unit: mm



Unit: mm

●Die Bonding Layout



- •Front view of the packaging.
- ·Dimensions are design values.
- ·If the heat sink is to be installed, it should be in contact with the die bonding point.

Unit: mm

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